Lattice Semiconductor Corporation - LFSC3GA40E-7FF1152C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga40e-7ff1152c

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

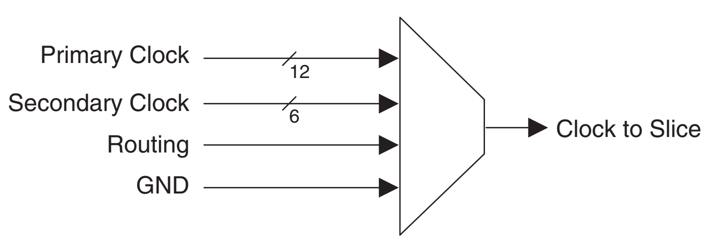
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



Note: GND is available to switch off the network.

Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

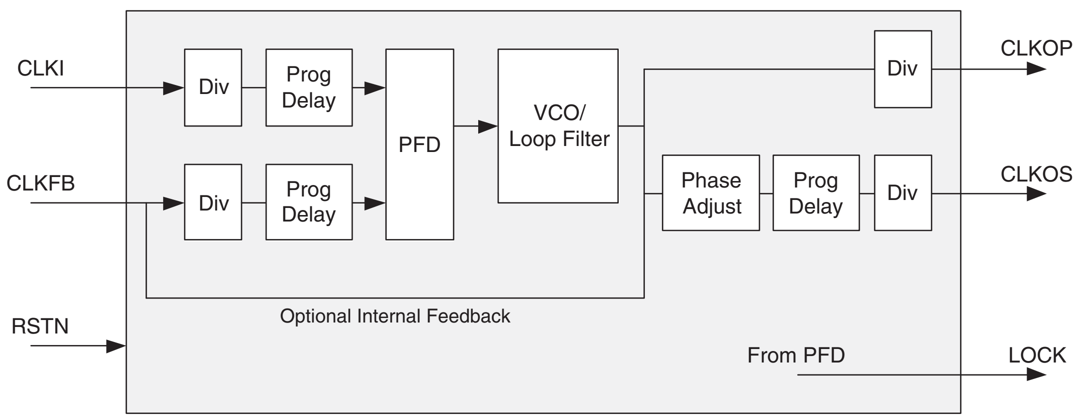
The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically.

The Phase Select block can modify the phase of the clock signal if desired. The Spread Spectrum block supports the modulation of the PLL output frequency. This reduces the peak energy in the fundamental and its harmonics providing for lower EMI (Electro Magnetic Interference).

The sysCLOCK PLL can be configured at power-up and then, if desired, reconfigured dynamically through the serial memory interface bus which connects with the on-chip system bus. For example, the user can select inputs, loop filters, divider setting, delay settings and phase shift settings. The user can also directly access the SMI bus through the routing.

The PLL clock input, from pin or routing, feeds into an input divider. There are four sources of feedback signal to the feedback divider: from the clock net, directly from the voltage controlled oscillator (VCO) output, from the routing or from an external pin. The signal from the input clock divider and the feedback divider are passed through the programmable delay before entering the phase frequency detector (PFD) unit. The output of this PFD is used to control the voltage controlled oscillator. There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-11 shows the sysCLOCK PLL diagram.

Figure 2-11. PLL Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Spread Spectrum Clocking (SSC)

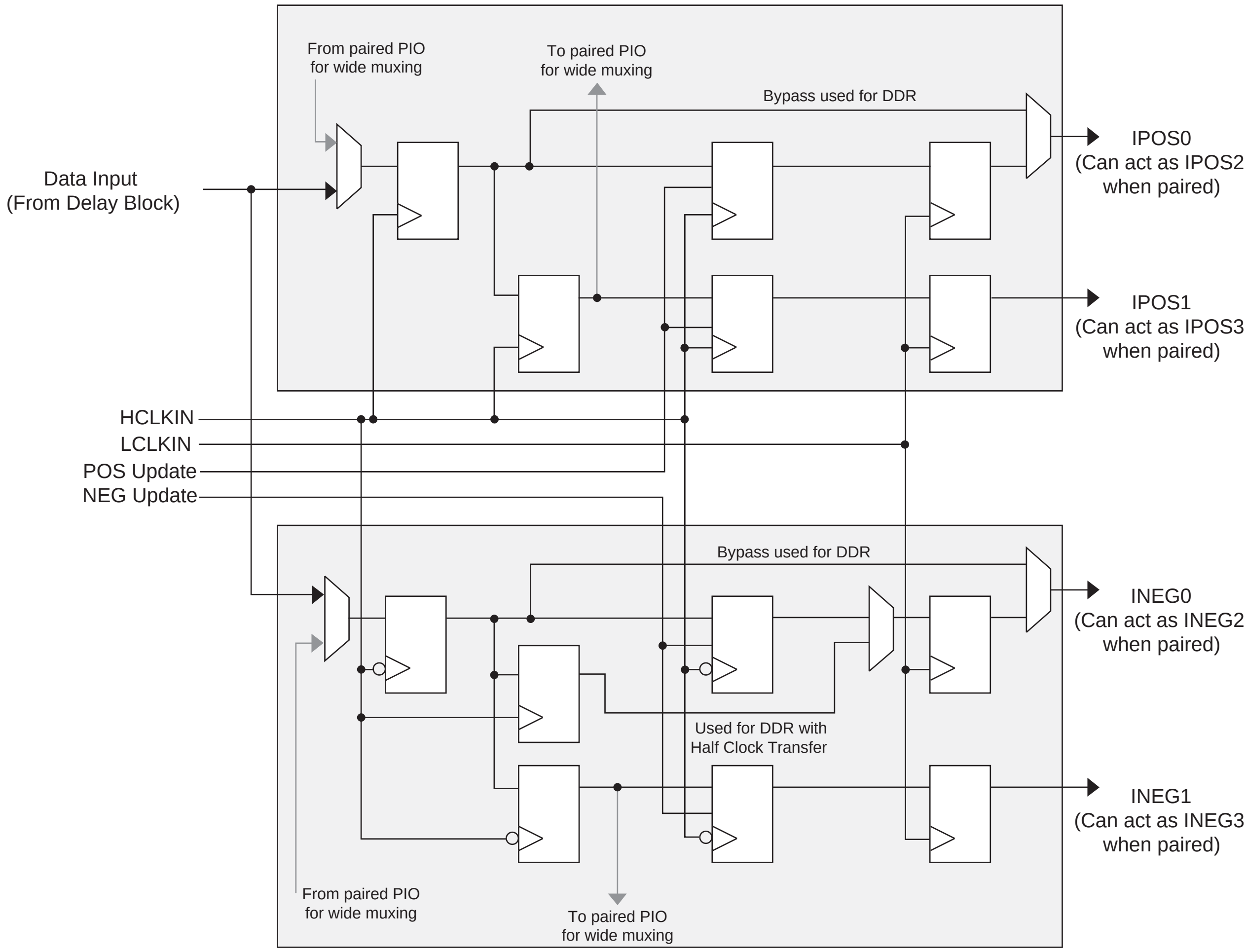
The PLL supports spread spectrum clocking to reduce peak EMI by using “down-spread” modulation. The spread spectrum operation will vary the output frequency (at 30KHz to 500KHz) in a range that is between its nominal value, down to a frequency that is a programmable 1%, 2%, or 3% lower than normal.

Digital Locked Loop (DLLs)

In addition to PLLs, the LatticeSC devices have up to 12 DLLs per device. DLLs assist in the management of clocks and strobes. DLLs are well suited to applications where the clock may be stopped or transferring jitter from input to output is important, for example forward clocked interfaces. PLLs are good for applications requiring the lowest output jitter or jitter filtering. All DLL outputs are routed as primary/edge clock sources.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. LOCK output signal is asserted when the DLL is locked. The ALU HOLD signal setting allows users to freeze the DLL at its current delay setting.

Figure 2-21. Input DDR/Shift Register Block



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the PURESPEED I/O buffers. The block contains a register for SDR operation and a group of registers for DDR and shift register operation. The output signal (DO) can be derived directly from one of the inputs (bypass mode), the SDR register or the DDR/shift register block. Figure 2-22 shows the diagram of the Output Register Block.

Output SDR Register/Latch Block

The SDR register operates on the positive edge of the high-speed clock. It has clock enable that is driven by the clock enable output signal generated by the control MUX. In addition it has a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR (LSR has precedence over CE) and Global Set Reset GSR enable or disable. The register LSR input is driven from LSRO, which is generated from the PIO control MUX. The GSR inputs is driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Output DDR/Shift Block

The DDR/Shift block contains registers and associated logic that support DDR and shift register functions using the high-speed clock and the associated transfer from the low-speed clock domain. It functions as a gearbox allowing low-speed parallel data from the FPGA fabric be output as a higher speed serial stream. Each PIO supports DDR and x2 shift functions. If desired PIOs A and B or C and D can be combined to form x4 shift functions. Figure 2-22 shows a simplified block diagram of the shift register block.

Table 2-6. Input/Output/Tristate Gearing Resource Rules

PIO	Input/Output Logic			Tri-State/Bidi	
	x1	x2	x4	x1	x2/x4
A	?	?	?	?	N/A
B	?	No I/O Logic	No I/O Logic	?	N/A
C	?	?	No I/O Logic	?	N/A
D	?	No I/O Logic	No I/O Logic	?	N/A

Note: Pin can still be used without I/O logic.

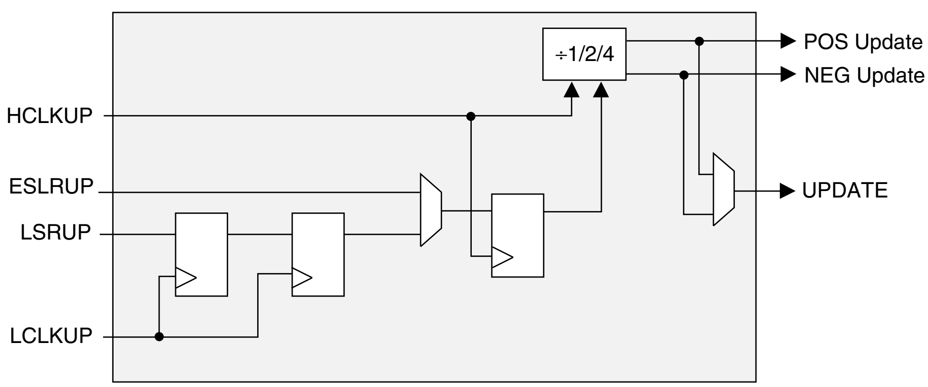
Control Logic Block

The control logic block allows the modification of control signals selected by the routing before they are used in the PIO. It can optionally invert all signals passing through it except the Global Set/Reset. Global Set/Reset can be enabled or disabled. It can route either the edge clock or the clock to the high-speed clock nets. The clock provided to the PIO by routing is used as the slow-speed clocks. In addition this block contains delays that can be inserted in the clock nets to enable Lattice's unique cycle boosting capability.

Update Block

The update block is used to generate the POS update and NEG update signals used by the DDR/Shift register blocks within the PIO. Note the update block is only required in shift modes. This is required in order to do the high speed to low speed handoff. One of these update signals is also selected and output from the PIC as the signal UPDATE. It consists of a shift chain that operates off either the high-speed input or output clock. The values of each register in the chain are set or reset depending on the desired mode of operation. The set/reset signal is generated from either the edge reset ELSR or the local reset LSR. These signals are optionally inverted by the Control Logic Block and provided to the update block as ELSRUP and LSRUP. The Lattice design tools automatically configure and connect the update block when one of the DDR or shift register primitives is used.

Figure 2-25. Update Block



PURESPEED I/O Buffer

Each I/O is associated with a flexible buffer referred to as PURESPEED I/O buffer. These buffers are arranged around the periphery of the device in seven groups referred to as Banks. The PURESPEED I/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL. The availability of programmable on-chip termination for both input and output use, further enhances the utility of these buffers.

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	0 <= V_{IN} <= V_{IH} (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7\ V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	$-3 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{CC} + 4 > V_{IN} \geq V_{CC} + 1$	$25 + (V_{IN} - V_{CC} -1)/0.015$	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

LatticeSC/M Internal Timing Parameters[1] (Continued)

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
EBR Timing									
t_{CO_EBR}	CK_Q_DEL	Clock (Read) to output from Address or Data	—	1.900	—	2.116	—	2.335	ns
t_{COO_EBR}	CK_Q_DEL	Clock (Write) to output from EBR output Register	0.390	—	0.444	—	0.498	—	ns
t_{SUDATA_EBR}	D_CK_SET	Setup Data to EBR Memory (Write clk)	-0.173	—	-0.192	—	-0.210	—	ns
t_{HDATA_EBR}	D_CK_HLD	Hold Data to EBR Memory (Write clk)	0.276	—	0.305	—	0.335	—	ns
t_{SUADDR_EBR}	A_CK_SET	Setup Address to EBR Memory (Write clk)	-0.165	—	-0.182	—	-0.200	—	ns
t_{HADDR_EBR}	A_CK_HLD	Hold Address to EBR Memory (Write clk)	0.269	—	0.298	—	0.327	—	ns
t_{SUWREN_EBR}	CE_CK_SET	Setup Write/Read Enable to EBR Memory (Write/Read clk)	0.225	—	0.226	—	0.226	—	ns
t_{HWREN_EBR}	CE_CK_HLD	Hold Write/Read Enable to EBR Memory (write/read clk)	0.073	—	0.095	—	0.116	—	ns
t_{SUCE_EBR}	CS_CK_SET	Clock Enable Setup Time to EBR Output Register (Read clk)	0.261	—	0.269	—	0.276	—	ns
t_{HCE_EBR}	CS_CK_HLD	Clock Enable Hold Time to EBR Output Register (Read clk)	0.023	—	0.039	—	0.055	—	ns
t_{RSTO_EBR}	RESET_Q_DEL	Reset To Output Delay Time from EBR Output Register (asynchronous)	—	0.589	—	0.673	—	0.757	ns
Cycle Boosting Timing									
t_{DEL1}	DEL1	Cycle boosting delay 1 applies to PIO, PFU, EBR	—	0.480	—	0.524	—	0.570	ns
t_{DEL2}	DEL2	Cycle boosting delay 2 applies to PIO, PFU, EBR	—	0.922	—	1.005	—	1.090	ns
t_{DEL3}	DEL3	Cycle boosting delay 3 applies to PIO, PFU, EBR	—	1.366	—	1.488	—	1.612	ns

1. Complete timing parameters for a user design will be incorporated when running ispLEVER. This is a sampling of the key timing parameters.

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_D	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2]

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F7	A_VDDAX25_L	-		A_VDDAX25_L	-	
B1	A_REFCLKP_L	-		A_REFCLKP_L	-	
C1	A_REFCLKN_L	-		A_REFCLKN_L	-	
D5	VCC12	-		VCC12	-	
A2	RESP_ULC	-		RESP_ULC	-	
E5	VCC12	-		VCC12	-	
D4	VCC12	-		VCC12	-	
H5	RESETN	1		RESETN	1	
H6	TSALLN	1		TSALLN	1	
G6	DONE	1		DONE	1	
G5	INITN	1		INITN	1	
F5	M0	1		M0	1	
F6	M1	1		M1	1	
F4	M2	1		M2	1	
E4	M3	1		M3	1	
D3	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
D2	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
J6	PL15C	7		PL16C	7	
J5	PL15D	7		PL16D	7	
E3	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
E2	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
K4	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
J4	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
F3	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
G3	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
K5	PL18C	7		PL18C	7	
K6	PL18D	7	VREF2_7	PL18D	7	VREF2_7
F2	PL19A	7		PL22A	7	
F1	PL19B	7		PL22B	7	
E1	PL19C	7		PL22C	7	
D1	PL19D	7		PL22D	7	
K3	PL22A	7		PL25A	7	
L3	PL22B	7		PL25B	7	
L6	PL22C	7	VREF1_7	PL25C	7	VREF1_7
M6	PL22D	7	DIFFR_7	PL25D	7	DIFFR_7
J1	PL23A	7	PCLKT7_1	PL26A	7	PCLKT7_1
K1	PL23B	7	PCLKC7_1	PL26B	7	PCLKC7_1
L1	PL24A	7	PCLKT7_0	PL27A	7	PCLKT7_0
M1	PL24B	7	PCLKC7_0	PL27B	7	PCLKC7_0
P8	PL24C	7	PCLKT7_2	PL27C	7	PCLKT7_2
R8	PL24D	7	PCLKC7_2	PL27D	7	PCLKC7_2
N2	PL26A	6	PCLKT6_0	PL29A	6	PCLKT6_0
N1	PL26B	6	PCLKC6_0	PL29B	6	PCLKC6_0
R7	PL26C	6	PCLKT6_1	PL29C	6	PCLKT6_1
R6	PL26D	6	PCLKC6_1	PL29D	6	PCLKC6_1

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D14	PT15B	1	A15/MPI_ADDR29	PT25B	1	A15/MPI_ADDR29
D13	PT15A	1	A17/MPI_ADDR31	PT25A	1	A17/MPI_ADDR31
F12	PT13D	1	A19/MPI_TSIZ1	PT24D	1	A19/MPI_TSIZ1
F13	PT13C	1	A20/MPI_BDIP	PT24C	1	A20/MPI_BDIP
B12	PT11B	1	A18/MPI_TSIZ0	PT24B	1	A18/MPI_TSIZ0
B11	PT11A	1	MPI_TEA	PT24A	1	MPI_TEA
E12	PT10D	1	D14/MPI_DATA14	PT23D	1	D14/MPI_DATA14
D12	PT10C	1	DP1/MPI_PAR1	PT23C	1	DP1/MPI_PAR1
G10	PT9B	1	A21/MPI_BURST	PT23B	1	A21/MPI_BURST
G9	PT9A	1	D15/MPI_DATA15	PT23A	1	D15/MPI_DATA15
C10	A_VDDIB3_L	-		A_VDDIB3_L	-	
E9	VCC12	-		VCC12	-	
B10	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A10	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
D9	VCC12	-		VCC12	-	
A9	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C9	A_VDDOB3_L	-		A_VDDOB3_L	-	
A8	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C8	A_VDDOB2_L	-		A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E8	VCC12	-		VCC12	-	
B8	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
B7	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
C7	A_VDDIB2_L	-		A_VDDIB2_L	-	
D8	VCC12	-		VCC12	-	
C6	A_VDDIB1_L	-		A_VDDIB1_L	-	
E7	VCC12	-		VCC12	-	
B6	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
B5	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A6	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
D7	VCC12	-		VCC12	-	
A5	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C5	A_VDDOB1_L	-		A_VDDOB1_L	-	
A4	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
C4	A_VDDOB0_L	-		A_VDDOB0_L	-	
A3	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E6	VCC12	-		VCC12	-	
B4	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
B3	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
C3	A_VDDIB0_L	-		A_VDDIB0_L	-	
D6	VCC12	-		VCC12	-	
L5	NC	-		PL21A	7	
M5	NC	-		PL21B	7	
G2	NC	-		PL20A	7	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH20	NC	-		PB51D	4	
AK27	NC	-		NC	-	
AJ24	NC	-		NC	-	
AF17	NC	-		PB42C	4	
AH27	NC	-		PB61B	4	
AD23	NC	-		PB57A	4	
AE23	NC	-		PB57B	4	
AH24	NC	-		PB59A	4	
AH25	NC	-		PB59B	4	
AH26	NC	-		PB61A	4	
AF24	NC	-		PB63A	4	
AG24	NC	-		PB63B	4	
AG25	NC	-		PB64A	4	
AF25	NC	-		PB64B	4	
AG26	NC	-		PB65A	4	
AF27	NC	-		PB65B	4	
AD28	NC	-		PR56B	3	
AC27	NC	-		PR56A	3	
AE29	NC	-		PR53B	3	
AD29	NC	-		PR53A	3	
AB30	NC	-		NC	-	
AA28	NC	-		NC	-	
Y27	NC	-		PR47C	3	
W27	NC	-		PR47D	3	
V30	NC	-		PR47A	3	
W30	NC	-		PR47B	3	
W26	NC	-		PR43D	3	
V26	NC	-		PR43C	3	
U25	NC	-		PR42C	3	
T27	NC	-		PR40B	3	
R27	NC	-		PR40A	3	
V27	NC	-		PR39B	3	
U27	NC	-		PR39A	3	
U29	NC	-		PR36B	3	
T29	NC	-		PR36A	3	
T24	NC	-		PR35C	3	
Y25	NC	-		PR48C	3	
P24	NC	-		NC	-	
K28	NC	-		NC	-	
P23	NC	-		NC	-	
L28	NC	-		NC	-	
M27	NC	-		PR21B	2	
L27	NC	-		PR21A	2	
H27	NC	-		PR20B	2	
G27	NC	-		PR20A	2	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E19	NC	-		NC	-	
G21	NC	-		NC	-	
G20	NC	-		NC	-	
G19	NC	-		NC	-	
F9	NC	-		NC	-	
A11	NC	-		NC	-	
G7	NC	-		NC	-	
AH9	NC	-		NC	-	
H8	VCC12	-		VCC12	-	
T8	VCC12	-		VCC12	-	
AB9	VCC12	-		VCC12	-	
AC8	VCC12	-		VCC12	-	
AB22	VCC12	-		VCC12	-	
AC23	VCC12	-		VCC12	-	
R23	VCC12	-		VCC12	-	
H23	VCC12	-		VCC12	-	
H15	VCC12	-		VCC12	-	
L24	VTT_2	2		VTT_2	2	
T23	VTT_2	2		VTT_2	2	
AC24	VTT_3	3		VTT_3	3	
T25	VTT_3	3		VTT_3	3	
W25	VTT_3	3		VTT_3	3	
AD24	VTT_4	4		VTT_4	4	
AE17	VTT_4	4		VTT_4	4	
AE18	VTT_4	4		VTT_4	4	
AC15	VTT_5	5		VTT_5	5	
AD16	VTT_5	5		VTT_5	5	
AE9	VTT_5	5		VTT_5	5	
AA6	VTT_6	6		VTT_6	6	
T7	VTT_6	6		VTT_6	6	
W6	VTT_6	6		VTT_6	6	
L7	VTT_7	7		VTT_7	7	
P7	VTT_7	7		VTT_7	7	
AA10	VCC	-		VCC	-	
AA11	VCC	-		VCC	-	
AA12	VCC	-		VCC	-	
AA13	VCC	-		VCC	-	
AA14	VCC	-		VCC	-	
AA17	VCC	-		VCC	-	
AA18	VCC	-		VCC	-	
AA19	VCC	-		VCC	-	
AA20	VCC	-		VCC	-	
AA21	VCC	-		VCC	-	
AA22	VCC	-		VCC	-	
AA9	VCC	-		VCC	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P22	VCCIO2	-		VCCIO2	-	
R22	VCCIO2	-		VCCIO2	-	
AA23	VCCIO3	-		VCCIO3	-	
AA24	VCCIO3	-		VCCIO3	-	
AB23	VCCIO3	-		VCCIO3	-	
AB24	VCCIO3	-		VCCIO3	-	
T22	VCCIO3	-		VCCIO3	-	
U22	VCCIO3	-		VCCIO3	-	
V22	VCCIO3	-		VCCIO3	-	
W22	VCCIO3	-		VCCIO3	-	
Y22	VCCIO3	-		VCCIO3	-	
Y23	VCCIO3	-		VCCIO3	-	
Y24	VCCIO3	-		VCCIO3	-	
AB16	VCCIO4	-		VCCIO4	-	
AB17	VCCIO4	-		VCCIO4	-	
AB18	VCCIO4	-		VCCIO4	-	
AB19	VCCIO4	-		VCCIO4	-	
AB20	VCCIO4	-		VCCIO4	-	
AC20	VCCIO4	-		VCCIO4	-	
AC21	VCCIO4	-		VCCIO4	-	
AC22	VCCIO4	-		VCCIO4	-	
AD20	VCCIO4	-		VCCIO4	-	
AD21	VCCIO4	-		VCCIO4	-	
AD22	VCCIO4	-		VCCIO4	-	
AB11	VCCIO5	-		VCCIO5	-	
AB12	VCCIO5	-		VCCIO5	-	
AB13	VCCIO5	-		VCCIO5	-	
AB14	VCCIO5	-		VCCIO5	-	
AB15	VCCIO5	-		VCCIO5	-	
AC10	VCCIO5	-		VCCIO5	-	
AC11	VCCIO5	-		VCCIO5	-	
AC9	VCCIO5	-		VCCIO5	-	
AD10	VCCIO5	-		VCCIO5	-	
AD11	VCCIO5	-		VCCIO5	-	
AD9	VCCIO5	-		VCCIO5	-	
AA7	VCCIO6	-		VCCIO6	-	
AA8	VCCIO6	-		VCCIO6	-	
AB7	VCCIO6	-		VCCIO6	-	
AB8	VCCIO6	-		VCCIO6	-	
T9	VCCIO6	-		VCCIO6	-	
U9	VCCIO6	-		VCCIO6	-	
V9	VCCIO6	-		VCCIO6	-	
W9	VCCIO6	-		VCCIO6	-	
Y7	VCCIO6	-		VCCIO6	-	
Y8	VCCIO6	-		VCCIO6	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

	LFSC/M15			LFSC/M25		
Ball Number	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y9	VCCIO6	-		VCCIO6	-	
J7	VCCIO7	-		VCCIO7	-	
J8	VCCIO7	-		VCCIO7	-	
K7	VCCIO7	-		VCCIO7	-	
K8	VCCIO7	-		VCCIO7	-	
L8	VCCIO7	-		VCCIO7	-	
L9	VCCIO7	-		VCCIO7	-	
M9	VCCIO7	-		VCCIO7	-	
N9	VCCIO7	-		VCCIO7	-	
P9	VCCIO7	-		VCCIO7	-	
R9	VCCIO7	-		VCCIO7	-	
A1	GND	-		GND	-	
A30	GND	-		GND	-	
AA15	GND	-		GND	-	
AA16	GND	-		GND	-	
AK1	GND	-		GND	-	
AK30	GND	-		GND	-	
K15	GND	-		GND	-	
K16	GND	-		GND	-	
L11	GND	-		GND	-	
L12	GND	-		GND	-	
L13	GND	-		GND	-	
L14	GND	-		GND	-	
L15	GND	-		GND	-	
L16	GND	-		GND	-	
L17	GND	-		GND	-	
L18	GND	-		GND	-	
L19	GND	-		GND	-	
L20	GND	-		GND	-	
M11	GND	-		GND	-	
M12	GND	-		GND	-	
M13	GND	-		GND	-	
M14	GND	-		GND	-	
M15	GND	-		GND	-	
M16	GND	-		GND	-	
M17	GND	-		GND	-	
M18	GND	-		GND	-	
M19	GND	-		GND	-	
M20	GND	-		GND	-	
N11	GND	-		GND	-	
N12	GND	-		GND	-	
N13	GND	-		GND	-	
N14	GND	-		GND	-	
N15	GND	-		GND	-	
N16	GND	-		GND	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W7	GND	-		GND	-	
AA14	VCC	-		VCC	-	
AA16	VCC	-		VCC	-	
AA17	VCC	-		VCC	-	
AA18	VCC	-		VCC	-	
AA19	VCC	-		VCC	-	
AA21	VCC	-		VCC	-	
AB13	VCC	-		VCC	-	
AB22	VCC	-		VCC	-	
N13	VCC	-		VCC	-	
N22	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	
P17	VCC	-		VCC	-	
P18	VCC	-		VCC	-	
P19	VCC	-		VCC	-	
P21	VCC	-		VCC	-	
R15	VCC	-		VCC	-	
R17	VCC	-		VCC	-	
R18	VCC	-		VCC	-	
R20	VCC	-		VCC	-	
T14	VCC	-		VCC	-	
T16	VCC	-		VCC	-	
T19	VCC	-		VCC	-	
T21	VCC	-		VCC	-	
U14	VCC	-		VCC	-	
U15	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U18	VCC	-		VCC	-	
U20	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
V14	VCC	-		VCC	-	
V15	VCC	-		VCC	-	
V17	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	
V21	VCC	-		VCC	-	
W14	VCC	-		VCC	-	
W16	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
Y15	VCC	-		VCC	-	
Y17	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN8	PB123B	4	
AG11	PB123C	4	
AG10	PB123D	4	
AP7	PB125A	4	
AP6	PB125B	4	
AG13	PB125C	4	
AG12	PB125D	4	
AN7	PB127A	4	
AN6	PB127B	4	
AK9	PB127C	4	
AK8	PB127D	4	
AP5	PB129A	4	
AP4	PB129B	4	
AD11	PB129C	4	
AE11	PB129D	4	
AM7	PB131A	4	
AM6	PB131B	4	
AJ9	PB131C	4	
AJ8	PB131D	4	
AP3	PB133A	4	
AN3	PB133B	4	
AF10	PB133C	4	
AE10	PB133D	4	
AL7	PB135A	4	
AL6	PB135B	4	
AK7	PB135C	4	
AK6	PB135D	4	
AN5	PB138A	4	
AN4	PB138B	4	
AH9	PB138C	4	VREF1_4
AH8	PB138D	4	
AM3	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AM4	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AG9	PB139C	4	
AG8	PB139D	4	
AN2	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AM2	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ6	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH6	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF7	PROBE_VCC	-	
AF8	PROBE_GND	-	
AG7	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AG6	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
D9	B_VDDIB2_R	-	
E12	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
F12	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
K11	VCC12	-	
A13	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
D12	B_VDDOB2_R	-	
B13	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
D13	B_VDDOB3_R	-	
B14	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
L11	VCC12	-	
A14	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
F13	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
E13	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
G13	VCC12	-	
E9	B_VDDIB3_R	-	
L13	VCC12	-	
J11	B_REFCLKN_R	-	
H11	B_REFCLKP_R	-	
M15	PT93D	1	HDC/SI
M16	PT93C	1	LDCN/SCS
F14	PT93B	1	D8/MPI_DATA8
G14	PT93A	1	CS1/MPI_CS1
L15	PT90D	1	D9/MPI_DATA9
L14	PT90C	1	D10/MPI_DATA10
D14	PT90B	1	CS0N/MPI_CS0N
E14	PT90A	1	RDN/MPI_STRB_N
L16	PT89D	1	WRN/MPI_WR_N
K16	PT89C	1	D7/MPI_DATA7
G15	PT89B	1	D6/MPI_DATA6
F15	PT89A	1	D5/MPI_DATA5
K14	PT87D	1	D4/MPI_DATA4
K13	PT87C	1	D3/MPI_DATA3
B15	PT87B	1	D2/MPI_DATA2
A15	PT87A	1	D1/MPI_DATA1
J14	PT86D	1	D16/PCLKC1_3/MPI_DATA16
H14	PT86C	1	D17/PCLKT1_3/MPI_DATA17
A16	PT86B	1	D0/MPI_DATA0
B16	PT86A	1	QOUT/CEON
J13	PT83D	1	VREF2_1
H13	PT83C	1	D18/MPI_DATA18
D15	PT83B	1	DOUT
E15	PT83A	1	MCA_DONE_IN
J16	PT81D	1	D19/PCLKC1_2/MPI_DATA19

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P38	PL26B	7		PL40B	7	
N35	PL26C	7		PL40C	7	
N36	PL26D	7		PL40D	7	
N39	PL29A	7		PL43A	7	
P39	PL29B	7		PL43B	7	
R34	PL29C	7	VREF1_7	PL43C	7	VREF1_7
T34	PL29D	7	DIFFR_7	PL43D	7	DIFFR_7
L41	PL30A	7		PL44A	7	
M41	PL30B	7		PL44B	7	
W29	PL30C	7		PL44C	7	
Y29	PL30D	7		PL44D	7	
L42	PL31A	7		PL45A	7	
M42	PL31B	7		PL45B	7	
U32	PL31C	7		PL45C	7	
V32	PL31D	7		PL45D	7	
R37	PL33A	7		PL47A	7	
T37	PL33B	7		PL47B	7	
M36	PL33C	7		PL47C	7	
M37	PL33D	7		PL47D	7	
P40	PL34A	7		PL48A	7	
N40	PL34B	7		PL48B	7	
R35	PL34C	7		PL48C	7	
T35	PL34D	7		PL48D	7	
N41	PL35A	7		PL49A	7	
P41	PL35B	7		PL49B	7	
V33	PL35C	7		PL49C	7	
U33	PL35D	7		PL49D	7	
R38	PL37A	7		PL51A	7	
T38	PL37B	7		PL51B	7	
R36	PL37C	7		PL51C	7	
T36	PL37D	7		PL51D	7	
N42	PL38A	7		PL52A	7	
P42	PL38B	7		PL52B	7	
Y31	PL38C	7		PL52C	7	
AA31	PL38D	7		PL52D	7	
U37	PL39A	7		PL53A	7	
V37	PL39B	7		PL53B	7	
U34	PL39C	7		PL53C	7	
V34	PL39D	7		PL53D	7	
U39	PL41A	7		PL55A	7	
T39	PL41B	7		PL55B	7	
V35	PL41C	7		PL55C	7	
W35	PL41D	7		PL55D	7	
R41	PL42A	7		PL56A	7	
T41	PL42B	7		PL56B	7	

Conventional Packaging

Commercial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-7F256C	-7	fpBGA	256	COM	15.2
LFSC3GA15E-6F256C	-6	fpBGA	256	COM	15.2
LFSC3GA15E-5F256C	-5	fpBGA	256	COM	15.2
LFSC3GA15E-7F900C	-7	fpBGA	900	COM	15.2
LFSC3GA15E-6F900C	-6	fpBGA	900	COM	15.2
LFSC3GA15E-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-7F256C	-7	fpBGA	256	COM	15.2
LFSCM3GA15EP1-6F256C	-6	fpBGA	256	COM	15.2
LFSCM3GA15EP1-5F256C	-5	fpBGA	256	COM	15.2
LFSCM3GA15EP1-7F900C	-7	fpBGA	900	COM	15.2
LFSCM3GA15EP1-6F900C	-6	fpBGA	900	COM	15.2
LFSCM3GA15EP1-5F900C	-5	fpBGA	900	COM	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-7F900C	-7	fpBGA	900	COM	25.4
LFSC3GA25E-6F900C	-6	fpBGA	900	COM	25.4
LFSC3GA25E-5F900C	-5	fpBGA	900	COM	25.4
LFSC3GA25E-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSC3GA25E-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSC3GA25E-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-7F900C	-7	fpBGA	900	COM	25.4
LFSCM3GA25EP1-6F900C	-6	fpBGA	900	COM	25.4
LFSCM3GA25EP1-5F900C	-5	fpBGA	900	COM	25.4
LFSCM3GA25EP1-7FF1020C[1]	-7	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-6FF1020C[1]	-6	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-5FF1020C[1]	-5	Organic fcBGA	1020	COM	25.4
LFSCM3GA25EP1-7FFA1020C	-7	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-6FFA1020C	-6	Organic fcBGA Revision 2	1020	COM	25.4
LFSCM3GA25EP1-5FFA1020C	-5	Organic fcBGA Revision 2	1020	COM	25.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FF1020I[1]	-6	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FF1020I[1]	-5	Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FC1152I[2]	-6	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FC1152I[2]	-5	Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FC1152I[1]	-6	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FC1152I[1]	-5	Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FC1704I[1]	-6	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FC1704I[1]	-5	Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FC1152I[1]	-6	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FC1152I[1]	-5	Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FF1152I	-6	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FF1152I	-5	Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FC1704I[1]	-6	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FC1704I[1]	-5	Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FF1704I	-6	Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FF1704I	-5	Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.